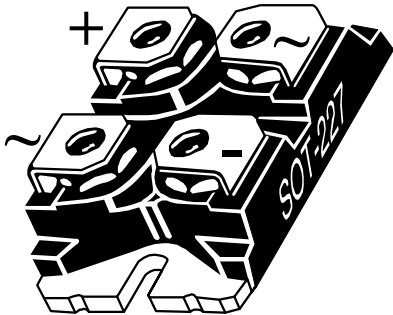
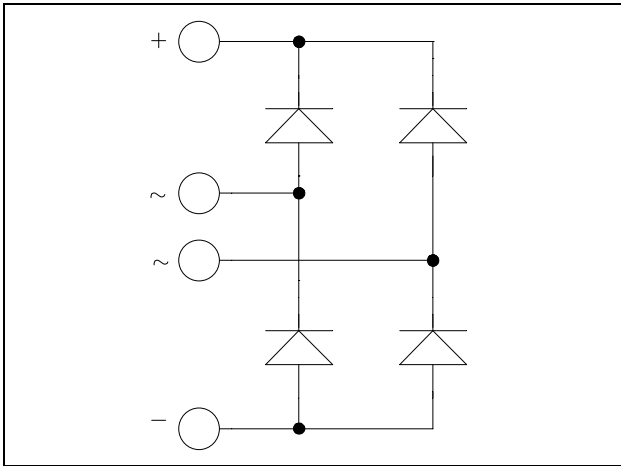


## ISOTOP<sup>®</sup> Fast Diode Full Bridge Power Module

**$V_{RRM} = 600V$**   
 **$I_C = 60A @ T_c = 80^{\circ}C$**



### Application

- Switch mode power supplies rectifier
- Induction heating
- Welding equipment
- High speed rectifiers

### Features

- Ultra fast recovery times
- Soft recovery characteristics
- High blocking voltage
- High current
- Low leakage current
- Very low stray inductance
- High level of integration
- ISOTOP<sup>®</sup> Package (SOT-227)

### Benefits

- Outstanding performance at high frequency operation
- Low losses
- Low noise switching
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- RoHS Compliant

### Absolute maximum ratings

Symbol	Parameter	Max ratings	Unit	
$V_R$	Maximum DC reverse Voltage	600	V	
$V_{RRM}$	Maximum Peak Repetitive Reverse Voltage			
$I_{F(AV)}$	Maximum Average Forward Current	Duty cycle = 50%	A	
		$T_C = 25^{\circ}C$		90
		$T_C = 80^{\circ}C$	60	
$I_{FSM}$	Non-Repetitive Forward Surge Current	8.3ms	$T_J = 45^{\circ}C$	500

**CAUTION:** These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed. See application note APT0502 on [www.microsemi.com](http://www.microsemi.com)

All ratings @  $T_j = 25^\circ\text{C}$  unless otherwise specified

**Electrical Characteristics**

<i>Symbol</i>	<i>Characteristic</i>	<i>Test Conditions</i>	<i>Min</i>	<i>Typ</i>	<i>Max</i>	<i>Unit</i>
$V_F$	Diode Forward Voltage	$I_F = 60\text{A}$		1.7	2.3	V
		$I_F = 120\text{A}$		2		
		$I_F = 60\text{A}$	$T_j = 125^\circ\text{C}$	1.4		
$I_{RM}$	Maximum Reverse Leakage Current	$V_R = 600\text{V}$	$T_j = 25^\circ\text{C}$		25	$\mu\text{A}$
			$T_j = 125^\circ\text{C}$		500	
$C_T$	Junction Capacitance	$V_R = 200\text{V}$		145		pF

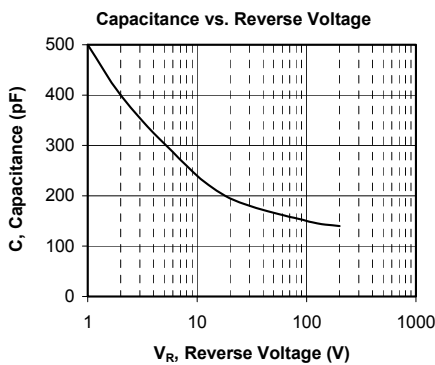
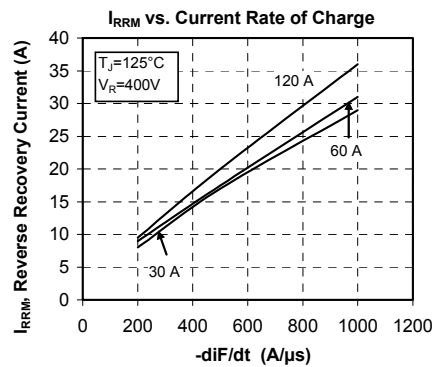
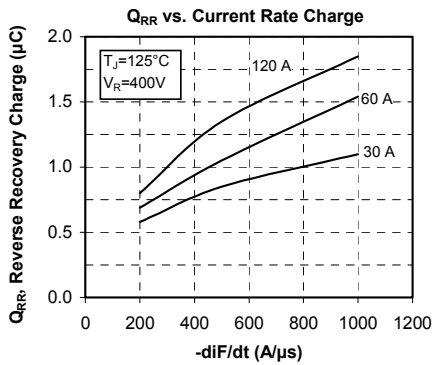
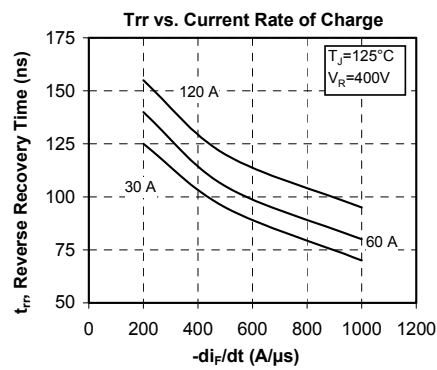
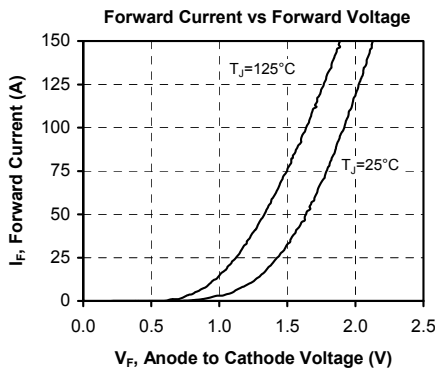
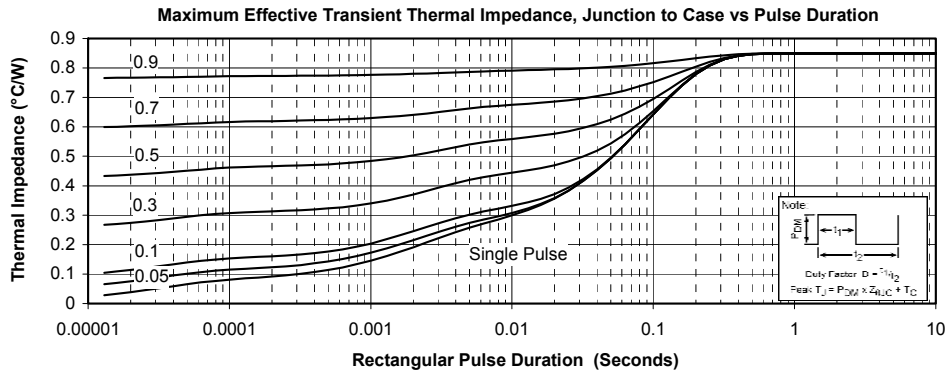
**Dynamic Characteristics**

<i>Symbol</i>	<i>Characteristic</i>	<i>Test Conditions</i>	<i>Min</i>	<i>Typ</i>	<i>Max</i>	<i>Unit</i>
$t_{rr}$	Reverse Recovery Time	$I_F = 60\text{A}$ $V_R = 400\text{V}$ $di/dt = 200\text{A}/\mu\text{s}$	$T_j = 25^\circ\text{C}$		70	ns
			$T_j = 125^\circ\text{C}$		140	
$Q_{rr}$	Reverse Recovery Charge		$T_j = 25^\circ\text{C}$		100	nC
			$T_j = 125^\circ\text{C}$		690	
$I_{RRM}$	Reverse Recovery Current		$T_j = 25^\circ\text{C}$		4	A
			$T_j = 125^\circ\text{C}$		9	
$t_{rr}$	Reverse Recovery Time	$I_F = 60\text{A}$ $V_R = 400\text{V}$ $di/dt = 1000\text{A}/\mu\text{s}$	$T_j = 125^\circ\text{C}$		80	ns
$Q_{rr}$	Reverse Recovery Charge				1540	nC
$I_{RRM}$	Reverse Recovery Current				31	A

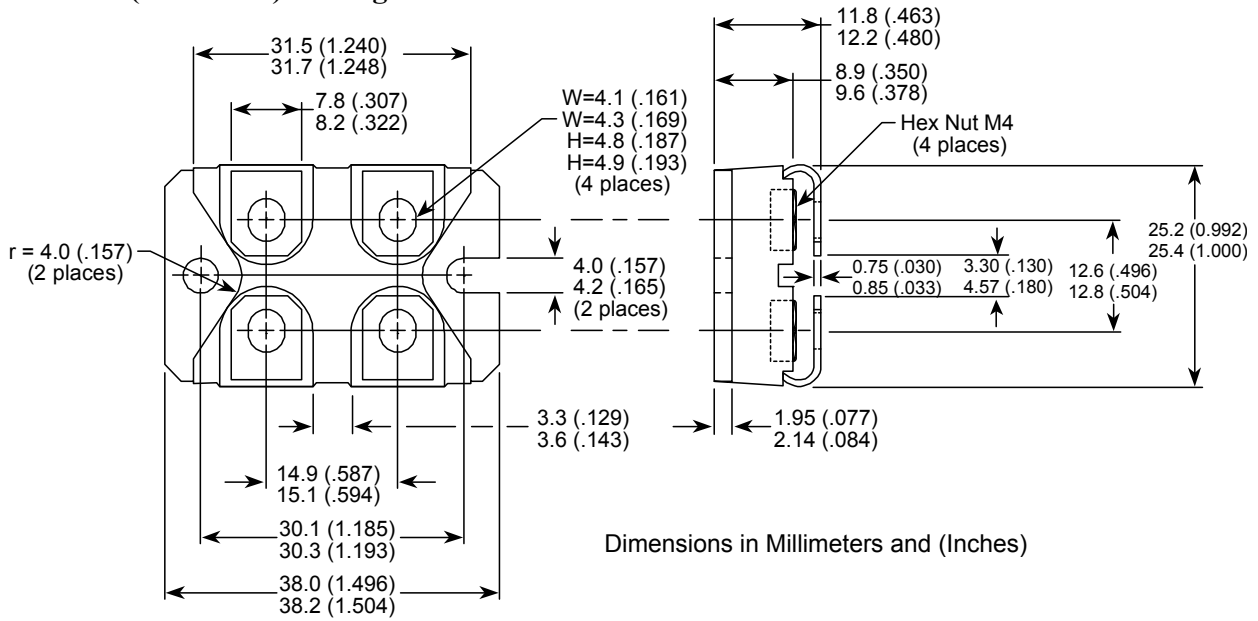
**Thermal and package characteristics**

<i>Symbol</i>	<i>Characteristic</i>	<i>Min</i>	<i>Typ</i>	<i>Max</i>	<i>Unit</i>
$R_{thJC}$	Junction to Case Thermal resistance			0.85	$^\circ\text{C}/\text{W}$
$R_{thJA}$	Junction to Ambient			20	$^\circ\text{C}/\text{W}$
$V_{ISOL}$	RMS Isolation Voltage, any terminal to case $t = 1$ min, 50/60Hz	2500			V
$T_J, T_{STG}$	Storage Temperature Range	-55		175	$^\circ\text{C}$
$T_L$	Max Lead Temp for Soldering: 0.063" from case for 10 sec			300	$^\circ\text{C}$
Torque	Mounting torque (Mounting = 8-32 or 4mm Machine and terminals = 4mm Machine)			1.5	N.m
Wt	Package Weight		29.2		g

## Typical Performance Curve



## SOT-227 (ISOTOP®) Package Outline



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